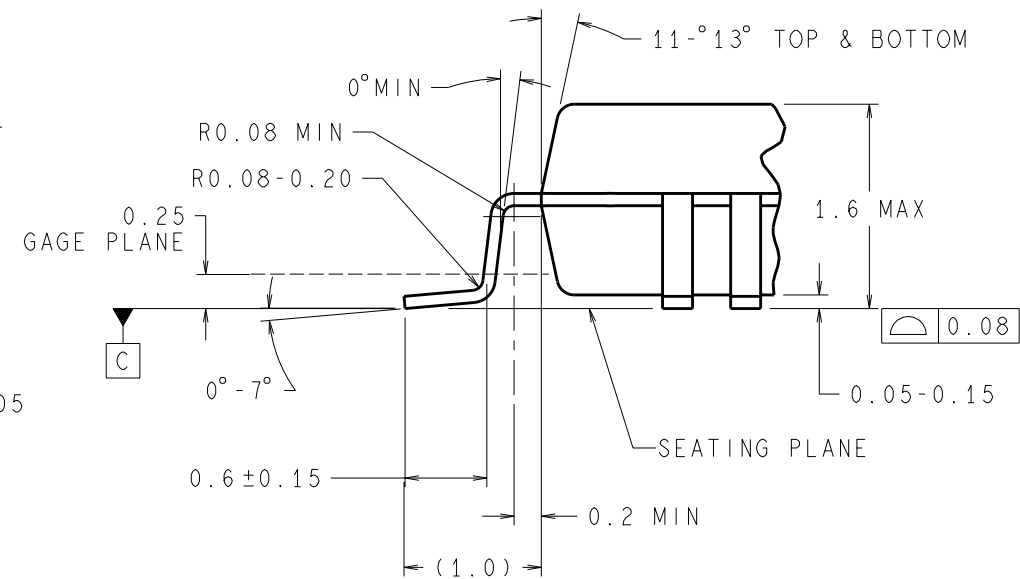
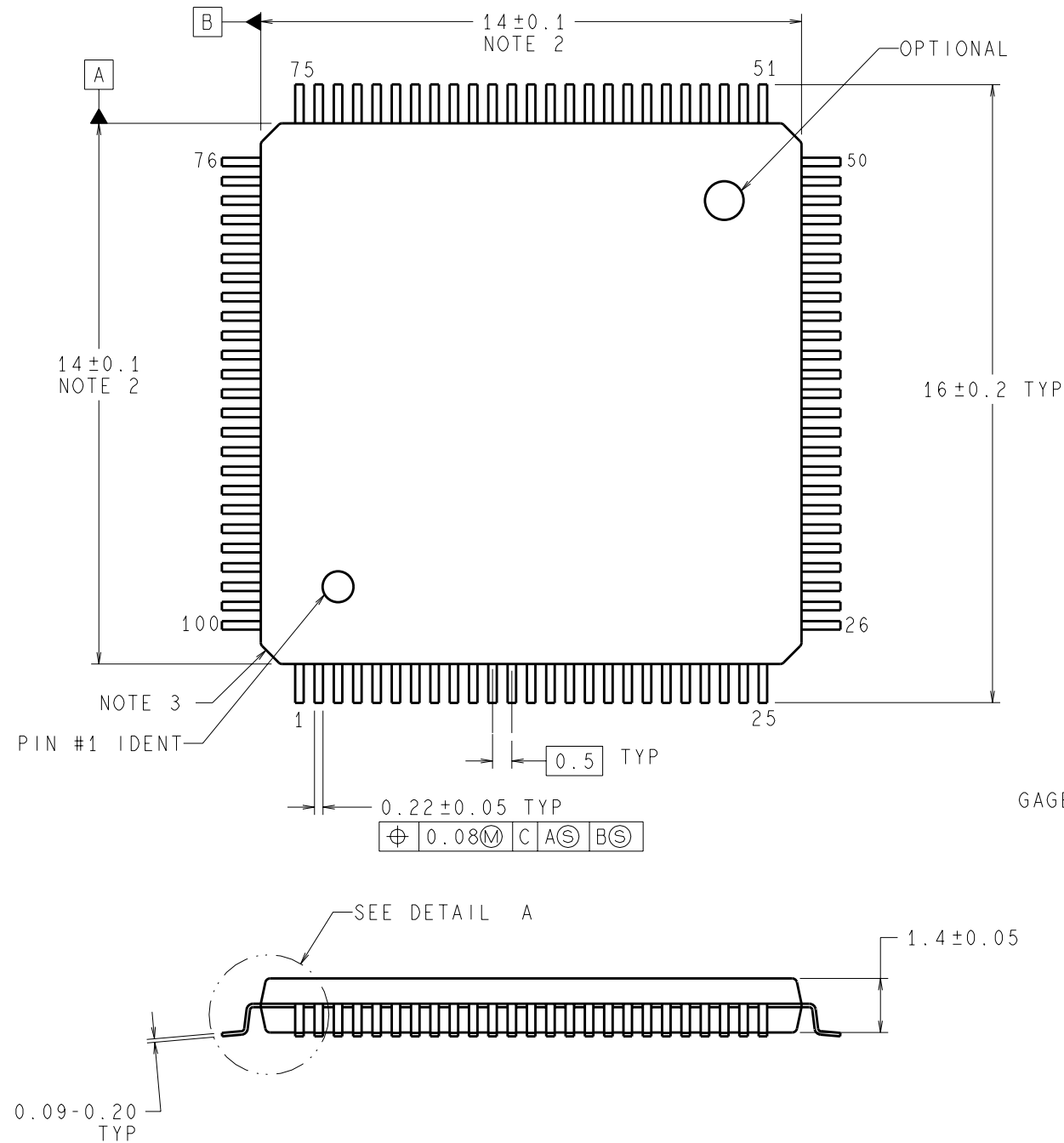


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
C	REVISE & REDRAW PER NEW STD; UPDATE TITLE	10496	08/10/1994	MS/HK
D	0.09-0.20 TYP WAS 0.09±0.20 TYP	10775	01/23/1995	KES/HJK
E	TITLE: LOFP WAS PQFP; UPDATE NOTE 4; ADD GEOMETRIC TOLERANCE	12317	12/02/1999	ACS/MS/RW



DETAIL A  
TYPICAL, SCALE: 30X

DIMENSIONS ARE IN MILLIMETERS

NOTES UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:  
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)  
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.  
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- THE CHAMFER AT PIN #1 CAN BE LARGER THAN OTHER 3 CHAMFERS.
- REFERENCE JEDEC REGISTRATION MS-026, VARIATION BED,  
DATED FEB 1999.

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DRAWN MARTA SUCHY	08/10/1994				
DFTG. CHK. THANH LEQUANG	12/07/1999				
ENGR. CHK. RANDALL WALBERG	12/07/1999	<b>LOFP, JEDEC METRIC, 14 X 14 X 1.4mm, 100 LEAD</b>			
 PROJECTION INCH [MM]					SCALE N/A
FORMERLY:		SHEET 1 of 1			